

Case No. 10322-31**DECLARATION FOR PATENT APPLICATION**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled Microdischarge Devices and Arrays Having Tapered Microcavities, the specification of which:

- ☐ is attached hereto.
☒ was filed on January 15, 2002 as Application Serial No. 10/047,469.
☐ and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability as defined in Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)Priority Claimed

(Number)	(Country)	(Day/Month/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No

I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below:

(Application Serial No.)	(Filing Date)

I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application:

(Application Serial No.)	(Filing Date)	(Status-patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Inventor's Signature

Full name of sole or first inventor

Residence

Citizenship

Post Office Address

J. Gary Eden

314 CR 2650N, Mahomet, Illinois 61853

United States

314 CR 2650N, Mahomet, Illinois 61853

Date: MARCH 13, 2002

BRINKS HOFER GILSON & LIONE

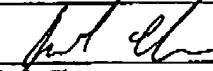
P.O. Box 10395
 Chicago, IL 60610
 (312) 321-4200

Case No. 10322-31

Inventor's Signature
Full name of second joint inventor, if any
Residence
Citizenship
Post Office Address

Date: _____
Sung-Jin Park
Sin-il APT. #203-1003, Young-Duk, Ki-Heung, Yong-In, Korea 449-741
Korea
Sin-il APT. #203-1003, Young-Duk, Ki-Heung, Yong-In, Korea 449-741

Inventor's Signature
Full name of third joint inventor
Residence
Citizenship
Post Office Address

Date: 3/27/2002

Jack Chen Urbana 61801 I.C.
1209 E. Florida, #21b, Champaign, Illinois 61820
United States Urbana 61801 I.C.
1209 E. Florida, #21b, Champaign, Illinois 61820

Inventor's Signature
Full name of fourth joint inventor
Residence
Citizenship
Post Office Address

Date: _____
Chang Liu
1828 Tahoe Ct., Champaign, Illinois 61820
China
1828 Tahoe Ct., Champaign, Illinois 61820

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Inventor's Signature

Full name of sole or first inventor

Residence

Citizenship

Post Office Address

Date:

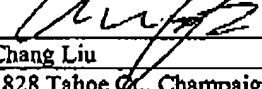
J. Gary Eden
314 CR 2650N, Mahomet, Illinois 61853
United States
314 CR 2650N, Mahomet, Illinois 61853

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P.O. Box 10395
Chicago, IL 60610
(312) 321-4200

Case No. 10322-31

Inventor's Signature	_____	Date:	_____
Full name of second joint inventor, if any	<u>Sung-Jin Park</u>		
Residence	<u>Sin-il APT. #203-1003, Young-Duk, Ki-Heung, Yong-In, Korea 449-741</u>		
Citizenship	<u>Korea</u>		
Post Office Address	<u>Sin-il APT. #203-1003, Young-Duk, Ki-Heung, Yong-In, Korea 449-741</u>		

Inventor's Signature	_____	Date:	_____
Full name of third joint inventor	<u>Jack Chen</u>		
Residence	<u>1209 E. Florida, #21b, Champaign, Illinois 61820</u>		
Citizenship	<u>United States</u>		
Post Office Address	<u>1209 E. Florida, #21b, Champaign, Illinois 61820</u>		

Inventor's Signature		Date:	<u>3/14/02</u>
Full name of fourth joint inventor	<u>Chang Liu</u>		
Residence	<u>1828 Tahoe Ct., Champaign, Illinois 61820 2 C.L.</u>		
Citizenship	<u>China</u>		
Post Office Address	<u>1828 Tahoe Ct., Champaign, Illinois 61820 2 C.L.</u>		

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Inventor's Signature

Date: _____

Full name of sole or first inventor

J. Gary Eden

Residence

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Citizenship

United States

Post Office Address

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P.O. Box 10395

Chicago, IL 60610

(312) 321-4200

Inventor's Signature
Full name of second joint inventor, if any
Residence
Citizenship
Post Office Address

P.S.J.
Mar 17 *Park*
Case No. 10322-31
Date: *Mar. 17. 2005*
Sung-Jin Park
Sin-il APT. #203-1003, Young-Duk, Ki-Heung, Yong-In, Korea 449-741
Korea
Sin-il APT. #203-1003, Young-Duk, Ki-Heung, Yong-In, Korea 449-741

Inventor's Signature
Full name of third joint inventor
Residence
Citizenship
Post Office Address

Jack Chen
Date:
1209 E. Florida, #21b, Champaign, Illinois 61820
United States
1209 E. Florida, #21b, Champaign, Illinois 61820

Inventor's Signature
Full name of fourth joint inventor
Residence
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Post Office Address

Chang Liu
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China
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